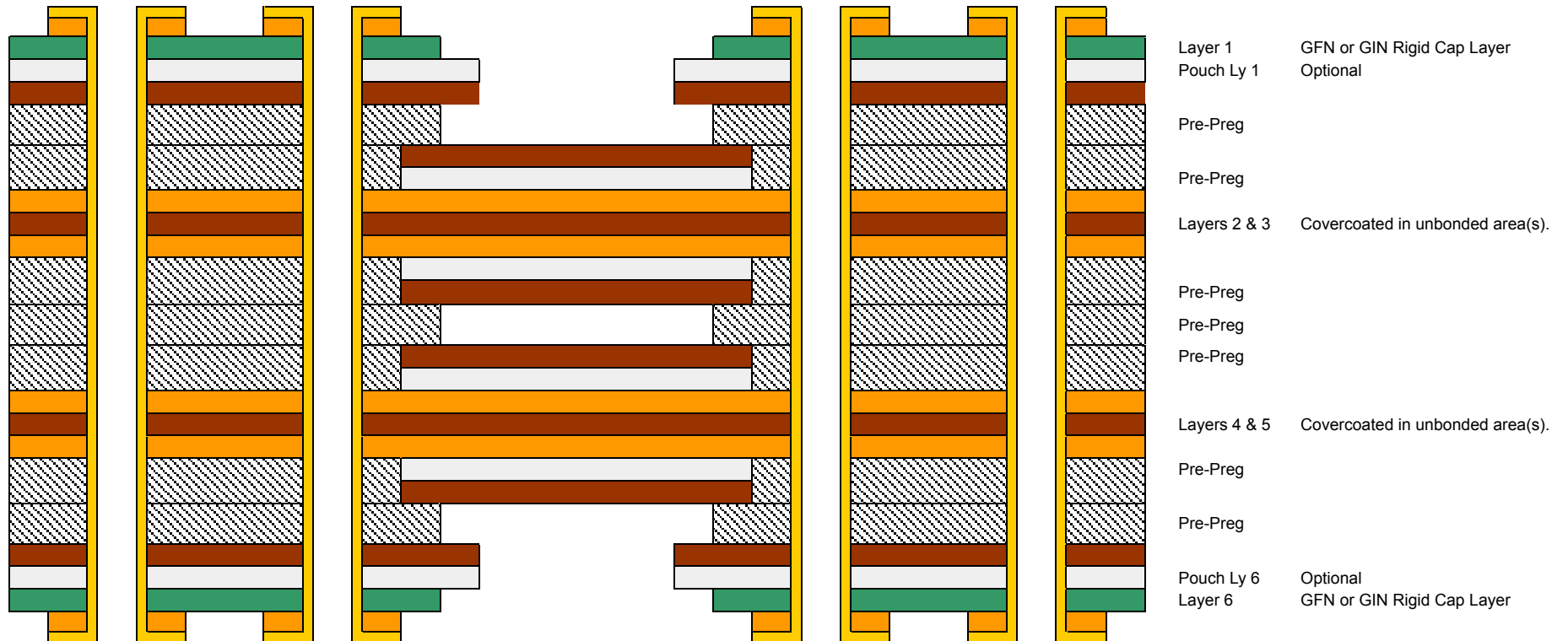








## Typical Material Stack up for Type 4 Multi-Layer Flex Circuits With Segmented Covercoats



- Layer 1 GFN or GIN Rigid Cap Layer  
Pouch Ly 1 Optional
- Pre-Preg
- Pre-Preg
- Layers 2 & 3 Covercoated in unbonded area(s).
- Pre-Preg
- Pre-Preg
- Pre-Preg
- Layers 4 & 5 Covercoated in unbonded area(s).
- Pre-Preg
- Pre-Preg
- Pouch Ly 6 Optional  
Layer 6 GFN or GIN Rigid Cap Layer

### Material Legend

-  Copper; Separately per IPC-4562/7 or as Clad Base Stock per IPC-4204/1 or IPC-4204/11
-  Adhesive; Separately per IPC 4203/18 or coated onto one or two sides of Kapton per IPC-4203/1
-  Kapton; Coated with Adhesive per IPC-4203/1 or Adhesiveless Base Stock Core per IPC-4204/11
-  Rigid Stiffener/ Cap Layer; Typically per IPC-4101/21, 24, 40, or 42
-  Pre-Preg Bond Ply; Typically per IPC-4101/21, 24, 40, or 42
-  Copper Plating; IPC-6013 / MIL-P-50884

Note: Adhesive or Adhesiveless  
Base Stocks may be used.  
Individual material layer thicknesses  
may be adjusted as required.